



Material Content Data Sheet



Halogen-Free

Sales Product Name	IST007N04NM6	Issued	23. June 2021
MA#	MA005447482		
Package	PG-HSOF-5-4	Weight*	370.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.845	1.04	1.04	10383	10383
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.08	13.09	130754	130924
wire	noble metal	gold	7440-57-5	0.034	0.01	0.01	93	93
encapsulation	inorganic material	zinc oxide	1314-13-2	1.397	0.38		3774	
	miscellaneous	miscellaneous	-	5.590	1.51		15095	
	plastics	epoxy resin	-	20.962	5.66		56608	
	inorganic material	silicon dioxide	60676-86-0	111.795	30.19	37.74	301907	377384
lead finish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9919	9919
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.068	0.02		185	
	noble metal	silver	7440-22-4	0.085	0.02		231	
	non noble metal	lead	7439-92-1	3.266	0.88	0.92	8820	9236
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		76	
	non noble metal	copper	7440-50-8	28.224	7.62	7.63	76220	76319
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		386	
	non noble metal	copper	7440-50-8	142.638	38.53	38.58	385199	385701
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com